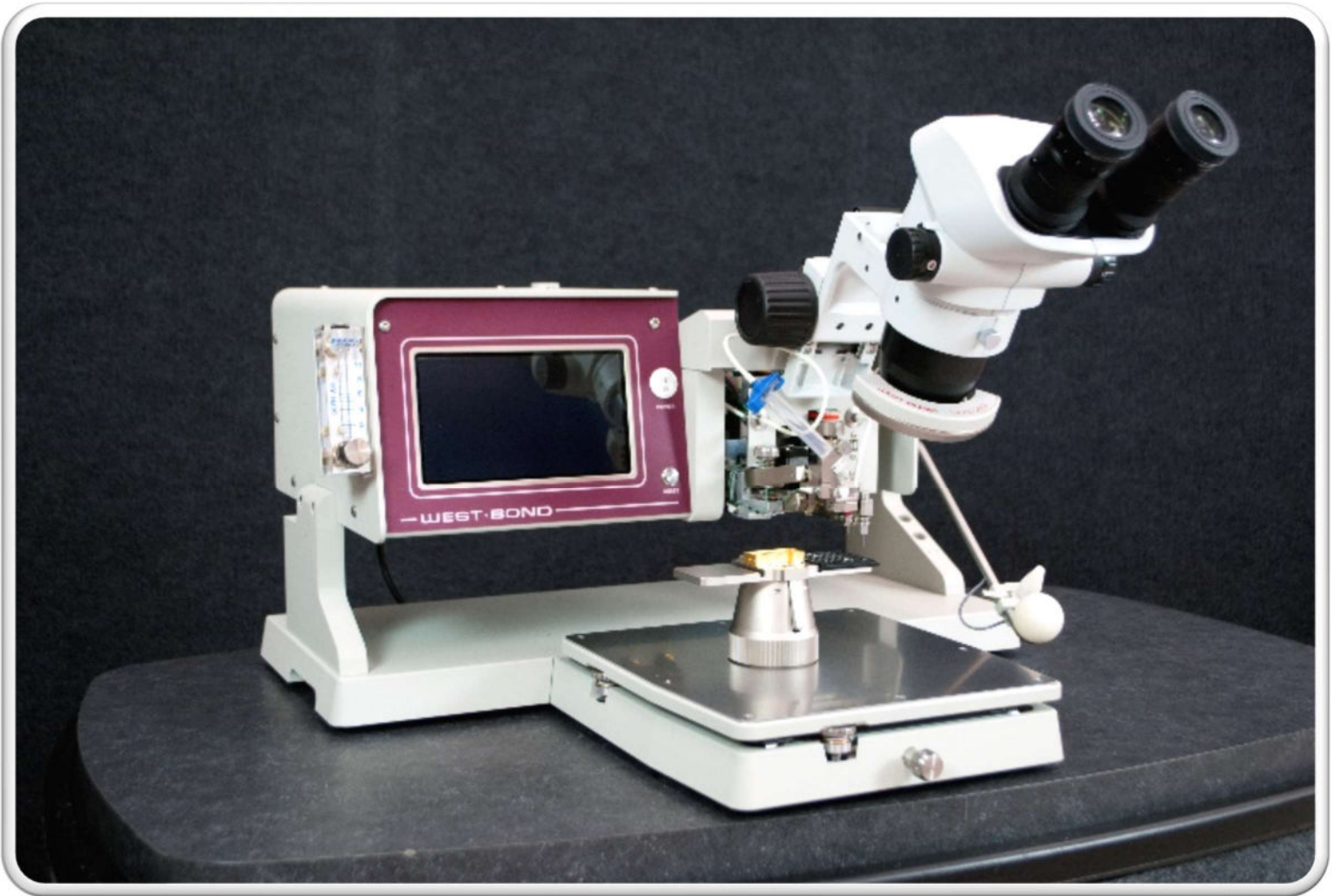


# WEST·BOND®



## 73KF

Convertible  
Epoxy Die Bonder  
&  
Eutectic Die Bonder

# WEST·BOND®

**UNLIMITED PART SIZE:** Access to remote bond targets on large packages, or modules, with WEST·BOND's throat-less chassis and micromanipulator design. This manual model can be configured to bond all types of applications from • Microwave • Semiconductor to • RF and • Hybrid production.



## CONVERTABILITY:

WEST·BOND introduced the first triple convertible wire bonder back in November of 1969. Today WEST·BOND utilizes the tool head design from the E series that can bond it all: Eutectic or Epoxy die attach.



## FEATURES:

Programmable force (15-150 grams), pure vertical Z, orthogonal X, Y, Z, 8:1 micromanipulator, pneumatic braking of all axes during bonding and programmable radiant tool heat. The system is available without the base and work platform as a 73KFX for tabletop or conveyor system. Risers are also available for extra tall parts.

## MACHINE SPECIFICATIONS:

Control Logic: Cortex M7 Microcontroller  
Memory: 2MB Solid State RAM  
Data Entry: 7" LCD Capacitive Touch Screen

## BOND AREA

ESD Protection: Conductive and dissipative  $10^6$   
Bond Platform: 11" x 11" (280 mm x 280 mm)  
Optional: 20" x 20" (508 mm x 508 mm)  
Z Travel: 14.3 mm / 12 $\mu$ m resolution  
XY Travel: 17.8 mm<sup>2</sup>  
Manual control via an 8:1 ratio micromanipulator

## TOOL CAPABILITY

Shank Length: 16 mm – Pick up Tool & Die Collet  
Tool Diameter: 1/16" (1.58mm)  
Disposable Syringe Setup: 3 or 5cc

## BOND PARAMETERS

Bond Force: 15 - 150 grams (programmable)  
Epoxy Flow Time: On or 1 – 1000 ms.  
Eutectic Scrub Direction L / R / Both  
Eutectic Scrub Stroke 1 – 20 mil (+/-)  
Eutectic Cycle 0 – 100

## FACILITY REQUIREMENTS

100 – 240 VAC 50/60Hz  
50 PSI clean dry air  
Min. 15inHg vacuum

**Dimensions:** 24" W x 22.5" D x 12.25" H

**Weight:** Crated with Accessories 53.5 kg (140lbs)